

## PRELIMINARY DATA SHEET

# NEC

Solid State Relay  
OCMOS FET

# PS7801K-1A

### 4-PIN ULTRA SMALL FLAT-LEAD, LOW OUTPUT CAPACITANCE (1.6 pF), 1-ch Optical Coupled MOS FET

#### DESCRIPTION

The PS7801K-1A is a low output capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 50% compared with the PS72xx series.

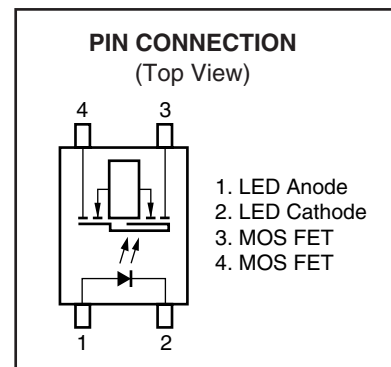
It is suitable for high-frequency signal control, due to its low off-state leakage current and low output capacitance.

#### FEATURES

- Ultra small flat-lead package (4.2 (L) × 2.5 (W) × 1.85 (H) mm)
- Low output capacitance ( $C_{out} = 1.6 \text{ pF TYP.}$ )
- Low off-state leakage current ( $I_{Loff} = 0.02 \text{ nA TYP.}$ )
- Break down voltage ( $V_L = 80 \text{ V}$ )
- High speed turn-on time ( $t_{on} = 0.06 \text{ ms TYP.}$ )
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Low offset voltage
- Ordering number of taping product: PS7801K-1A-F3, F4 (3 500 pcs/reel)
- Pb-Free product
- UL awaiting approval

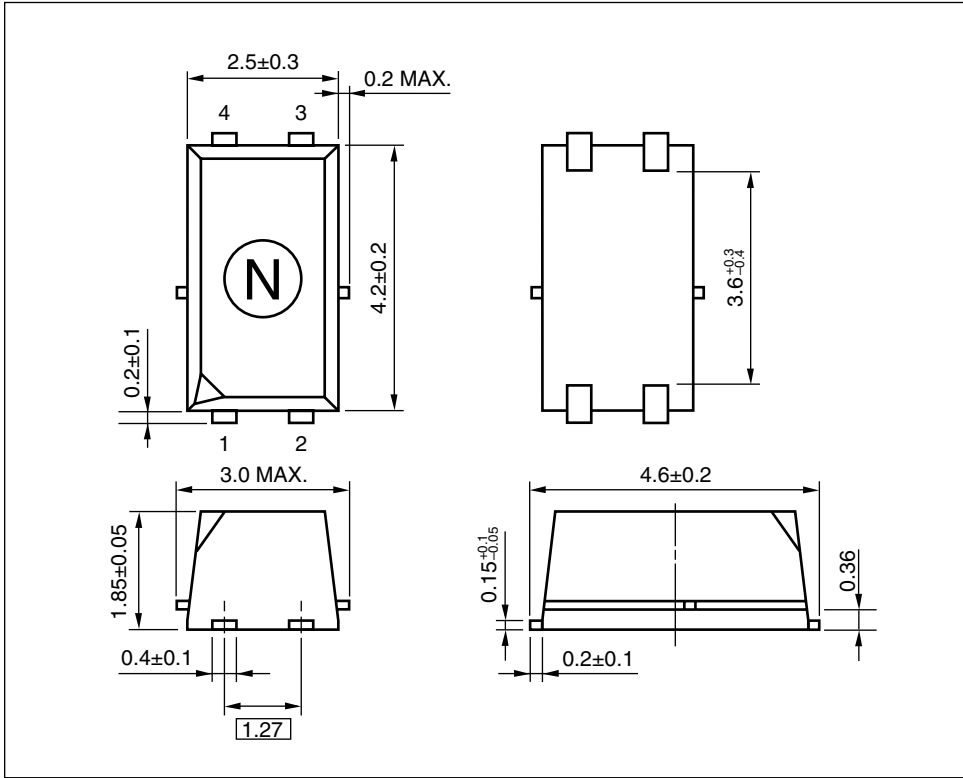
#### APPLICATIONS

- Measurement equipment

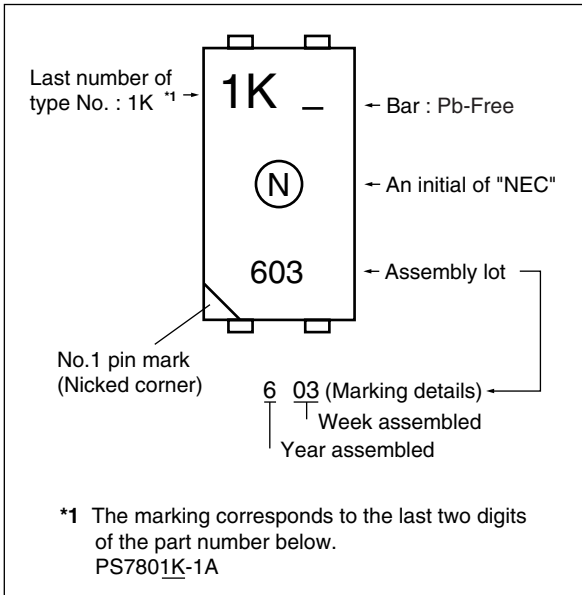


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PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



**ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS7801K-1A-F3	PS7801K-1A-F3-A	Pb-Free	Embossed Tape 3 500 pcs/reel	UL awaiting approval	PS7801K-1A
PS7801K-1A-F4	PS7801K-1A-F4-A				

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I <sub>F</sub>	50	mA
	Reverse Voltage	V <sub>R</sub>	5.0	V
	Power Dissipation	P <sub>D</sub>	50	mW
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	1	A
MOS FET	Break Down Voltage	V <sub>L</sub>	80	V
	Continuous Load Current	I <sub>L</sub>	40	mA
	Pulse Load Current <sup>*2</sup> (AC/DC Connection)	I <sub>LP</sub>	80	mA
	Power Dissipation	P <sub>D</sub>	250	mW
Isolation Voltage <sup>*3</sup>		BV	500	Vr.m.s.
Total Power Dissipation		P <sub>T</sub>	300	mW
Operating Ambient Temperature		T <sub>A</sub>	-40 to +85	°C
Storage Temperature		T <sub>stg</sub>	-40 to +100	°C

\*1 PW = 100 μs, Duty Cycle = 1%

\*2 PW = 100 ms, 1 shot

\*3 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output.  
Pins 1-2 shorted together, 3-4 shorted together.

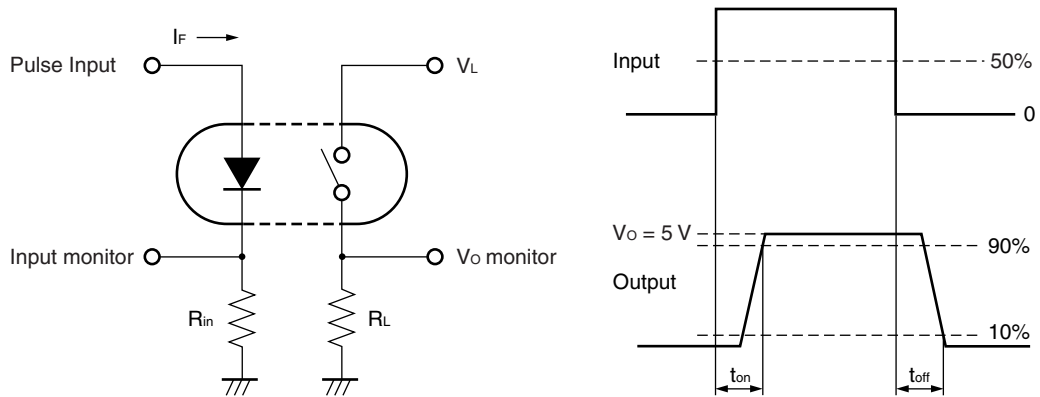
**RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 25°C)**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I <sub>F</sub>	2	5	20	mA
LED Off Voltage	V <sub>F</sub>	0		0.5	V

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 5 mA		1.1	1.4	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I <sub>Loff</sub>	V <sub>D</sub> = 80 V		0.02	1.0	nA
	Output Capacitance	C <sub>out</sub>	V <sub>D</sub> = 0 V, f = 1 MHz, t < 1 s		1.6	3.5	pF
Coupled	LED On-state Current	I <sub>Fon</sub>	I <sub>L</sub> = 40 mA			2.0	mA
	On-state Resistance	R <sub>on</sub>	I <sub>F</sub> = 5 mA, I <sub>L</sub> = 40 mA, t ≤ 10 ms		17.5	25	Ω
	Turn-on Time <sup>*1,2</sup>	t <sub>on</sub>	I <sub>F</sub> = 5 mA, V <sub>O</sub> = 5 V, R <sub>L</sub> = 500 Ω, PW ≥ 10 ms		0.06	0.25	ms
	Turn-off Time <sup>*1,2</sup>	t <sub>off</sub>			0.02	0.5	
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 0.5 kV <sub>DC</sub>	10 <sup>9</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.3		pF

**\*1 Test Circuit for Switching Time**

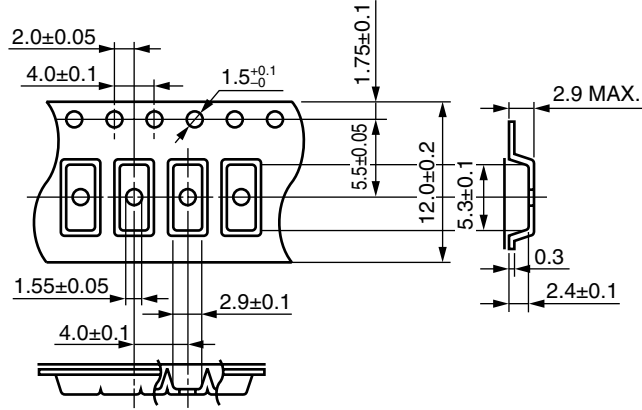


**\*2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

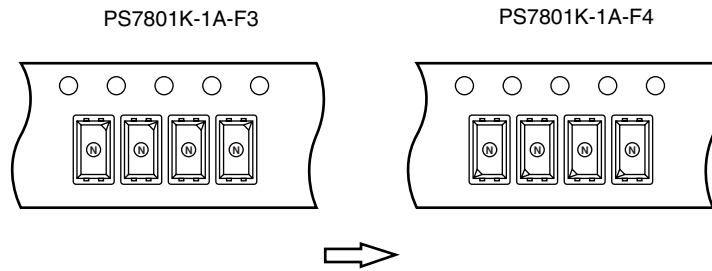
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TAPING SPECIFICATIONS (UNIT: mm)

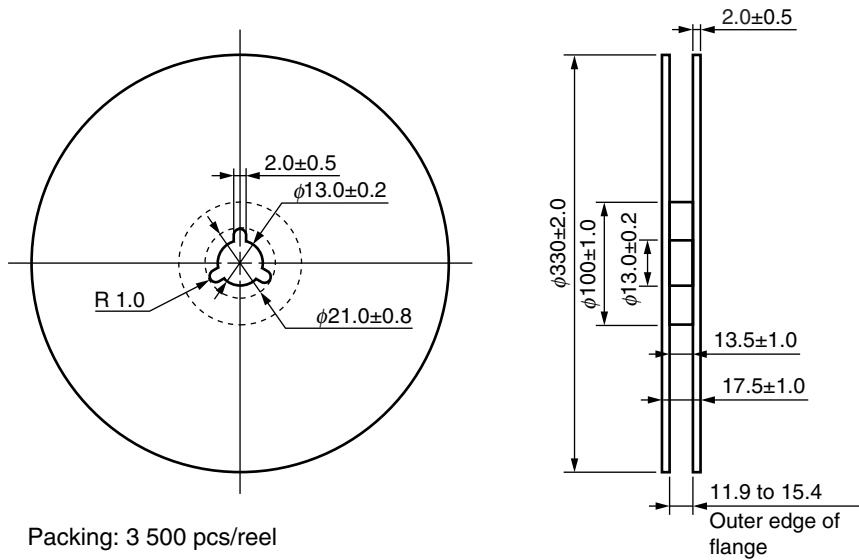
Outline and Dimensions (Tape)



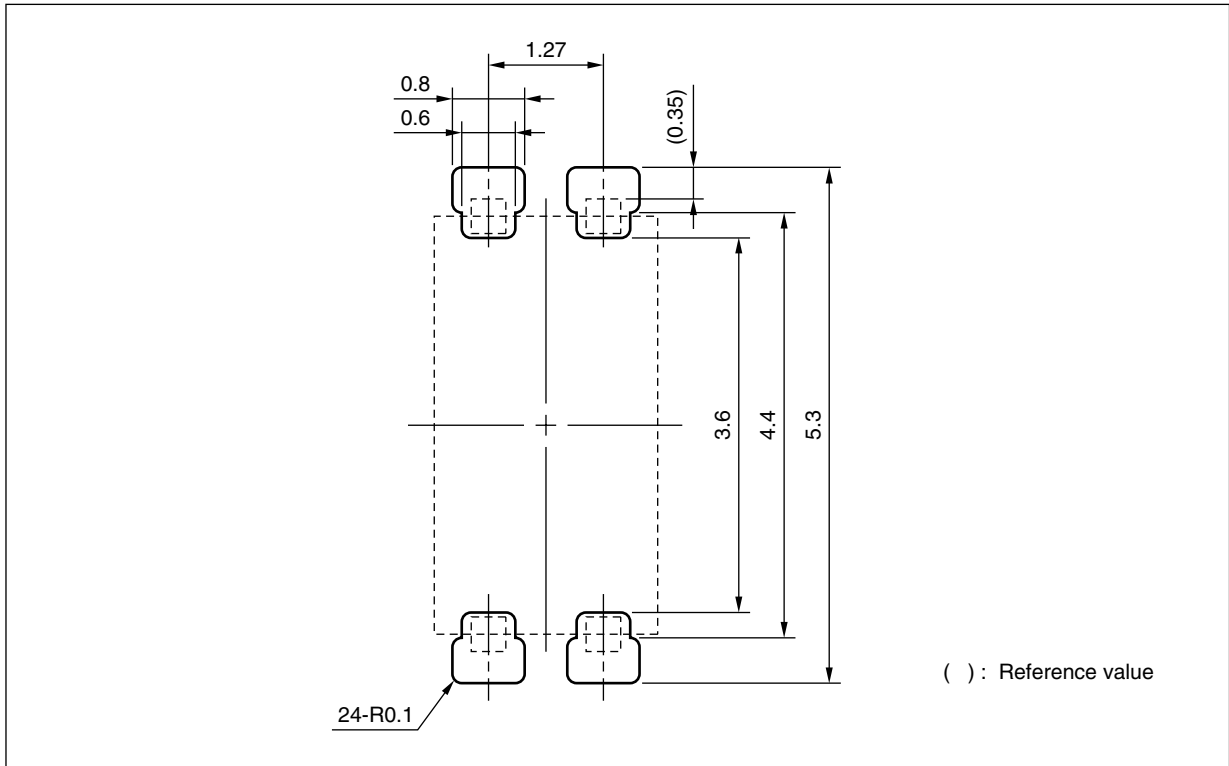
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



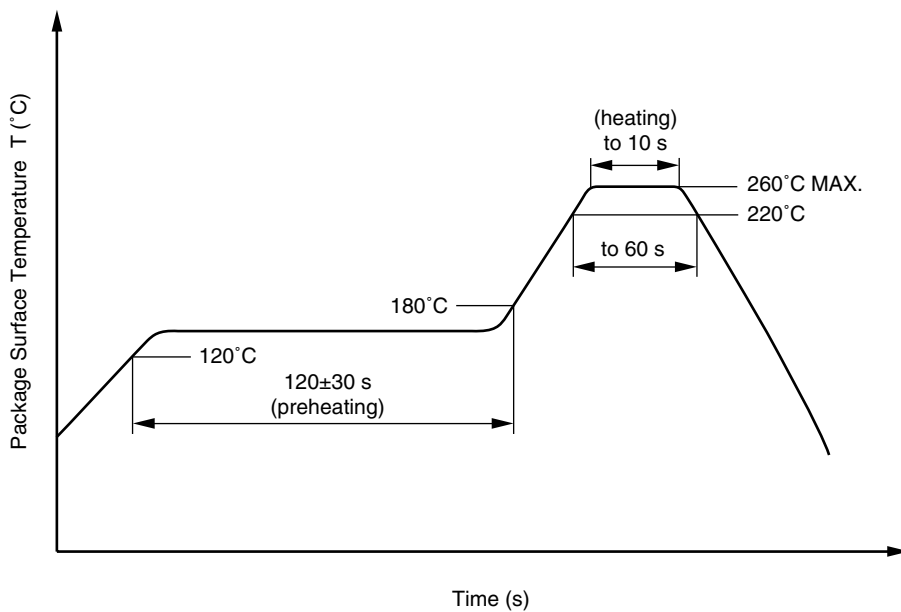
**Remark** All dimensions in this figure must be evaluated before use.

**RECOMMENDED SOLDERING CONDITIONS**

**(1) Infrared reflow soldering**

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



**(2) Wave soldering**

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

**(3) Cautions**

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

<p><b>Caution</b></p>	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.               <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> </li> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>
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